

#### **Device Features**

- Internally matched to 50 ohms
- Operated at 3.0V and 5.0V
- 37.5 dBm Output IP3 at 0dBm/tone at 700MHz
- 22.5dB Gain at 700MHz
- 21.1dBm P1dB at 700 MHz
- 0.43 dB NF at 700MHz on evaluation board
- Green/RoHS2 Compliant DFN8 2x2 Package

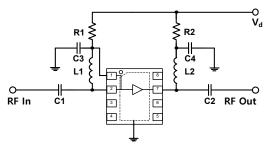
#### **Product Description**

BeRex's BLB01 is a high linearity LNA, based on GaAs material with E-pHEMT process and packaged in a RoHS2-compliant DFN 8L 2x2mm<sup>2</sup> Surface mount package. It is designed for use where low noise and high linearity are required and features low noise and high OIP3 at Frequency range of 0.5~1.5GHz. It is internally matched to 50 Ohms without external matching components, with fast enable switching speed for TD-LTE application. All devices are 100% RF/DC tested and classified as HBM ESD Class 1C.

#### **Applications**

- Base station Infrastructure/RFID
- Commercial/Industrial/Military wireless system
- TDD or FDD LTE systems

## **Applications Circuit**



\* Refer to page 14 for Enable application.

вом	Value	Size	Vendor
C1,C4	100pF	0603	Samsung
C2,C3	12pF	0603	Samsung
R1	6.8Kohm	0603	Samsung
R2	0 ohm	0603	Samsung
L1	27nH	0603	Taiyo Yuden
L2	82nH	0603	Taiyo Yuden

#### Part Marking (XX:Wafer number)



## **Electrical Specifications**

Device performance \_ measured on a BeRex evaluation board at 25°C, Vd=5V, 50  $\Omega$  system.

Parameter	Conditions	Min	Тур	Max	Unit
Operational Frequency Range		500		1500	MHz
Test Frequency			700		MHz
Gain		21.0	22.5		dB
Input Return Loss			-12.3		dB
Output Return Loss			-15.4		dB
Output IP3	$0  dBm / tone$ , $\Delta f$ =1 MHz	34.5	37.5		dBm
Output P1dB		20.1	21.1		dBm
Noise Figure			0.43	0.63	dB

<sup>\*</sup> NF: Losses on input and output transmission lines on PCB are not de-embedded.

Device performance  $\_$  measured on a BeRex evaluation board at 25°C, Vd=3V, 50  $\Omega$  system.

Parameter	Conditions	Min	Тур	Max	Unit
Operational Frequency Range		500		1500	MHz
Test Frequency			700		MHz
Gain		20.0	21.5		dB
Input Return Loss			-12.1		dB
Output Return Loss			-12.9		dB
Output IP3	$0 \text{ dBm / tone}$ , $\Delta f$ =1 MHz	27.5	30.5		dBm
Output P1dB		15.9	16.9		dBm
Noise Figure			0.44	0.64	dB

<sup>\*</sup> NF: Losses on input and output transmission lines on PCB are not de-embedded.

#### **Recommended Operating Conditions**

Parameter	Min	Тур	Max	Unit
Bandwidth	500		1500	MHz
$I_d @ (V_d = 5.0V)$	53	66	79	mA
$I_d @ (V_d = 3.0V)$	22	27	32	mA
$V_d$	3	5	5.25	V
dG/dT		-0.008		dB/°C
R <sub>TH</sub>		24.76		°C/W
Operating Case Temperature	-40		+105	°C
Switching Time(Ton)		140		ns
Switching Time(T <sub>off</sub> )		140		ns

Electrical specifications are measured at specified test conditions.

Specifications are not guaranteed over all recommended operating conditions.



## **Absolute Maximum Ratings**

Parameter	Rating	Unit
Storage Temperature	-55 to +155	°C
Junction Temperature	+160	°C
Supply Voltage	+6	V
Supply Current	130	mA
Input RF Power	21	dBm

Operation of this device above any of these parameters may result in permanent damage.

## Typical Performance (Vd=5.0V, Id=66mA, T=25°C)

Parameter		Frequency Unit					
V <sub>d</sub> = 5V	500	700	800	900	1500	MHz	
Gain	24.5	22.5	21.7	21	17.5	dB	
S11	-15.5	-12.3	-12.0	-11.7	-11.5	dB	
S22	-8.7	-15.4	-19.3	-22.5	-15.8	dB	
OIP3	38.0	37.5	35.5	35.5	32.5	dBm	
P1dB	21.2	21.1	21.2	20.9	19.3	dBm	
Noise Figure	0.6	0.43	0.4	0.44	0.7	dB	

<sup>\*</sup> NF: Losses on input and output transmission lines on PCB are not de-embedded.

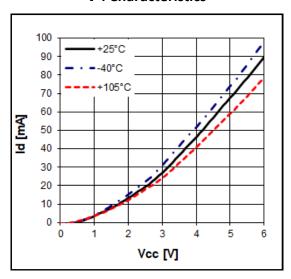
## Typical Performance (Vd=3.0V, Id=27mA, T=25°C)

Parameter		Frequency Unit						
$V_d = 3V$	500	700	800	900	1500	MHz		
Gain	23.3	21.4	20.5	19.7	16.1	dB		
S11	-18.3	-12.1	-11.0	-10.4	-9.3	dB		
S22	-7.4	-12.9	-15.0	-16.5	-13.7	dB		
OIP3	31.0	30.5	29.5	28.5	27.0	dBm		
P1dB	16.2	16.9	17.1	17.2	17.5	dBm		
Noise Figure	0.59	0.44	0.41	0.45	0.76	dB		

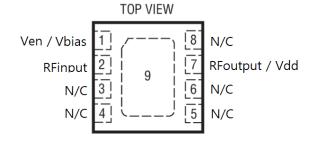
 $<sup>\</sup>ensuremath{^{*}}\xspace$  NF : Losses on input and output transmission lines on PCB are not de-embedded.



#### **V-I Characteristics**

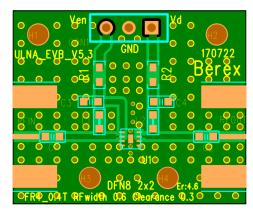


## **Pin Configuration**



 $\begin{array}{c} {\rm DC~PACKAGE} \\ {\rm 8-LEAD~(2mm\times2mm)~PLASTIC~DFN} \\ {\rm EXPOSED~PAD~(PIN~9)~IS~GND,~MUST~BE~SOLDERED~TO~PCB} \end{array}$ 

## **Evaluation Board**

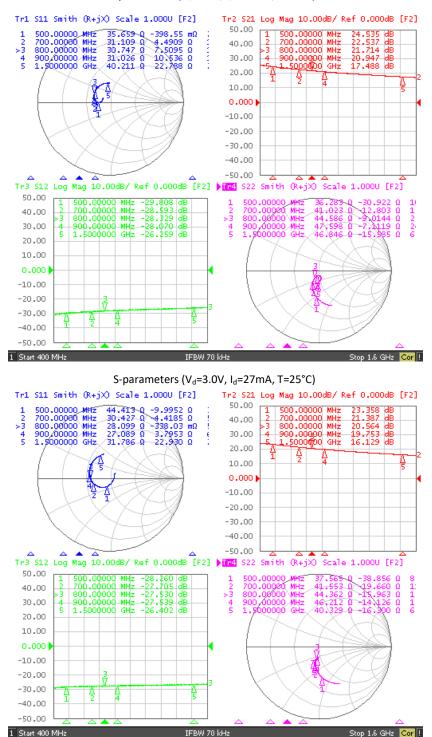


\*Dielectric constant \_ 4.2 \*RF pattern width 24mil \*16mil thick FR4 PCB



## **Typical Device Data**

S-parameters ( $V_d$ =5.0V,  $I_d$ =66mA , T=25°C)





## **S-Parameter**

(Vd=5.0V,Id = 66mA, T = 25 °C, calibrated to device leads)

Freq	S11	S11	S21	S21	S12	S12	S22	S22
[MHz]	Mag	Ang	Mag	Ang	Mag	Ang	Mag	Ang
500	0.23	-124.89	18.00	134.12	0.04	63.62	0.20	-119.48
600	0.29	-140.90	15.43	123.05	0.04	53.44	0.15	-142.56
700	0.30	-151.49	13.67	115.15	0.04	49.45	0.10	-161.73
800	0.31	-157.31	12.36	108.84	0.04	45.30	0.07	-177.33
900	0.30	-163.08	11.33	103.54	0.04	43.09	0.04	164.79
1000	0.29	-166.98	10.52	98.37	0.04	37.82	0.01	113.63
1100	0.28	-170.27	9.82	93.46	0.05	37.16	0.03	4.31
1200	0.27	-172.29	9.17	88.78	0.05	31.40	0.06	-13.23
1300	0.26	-173.09	8.66	84.16	0.05	31.93	0.09	-19.81
1400	0.24	-174.55	8.18	79.84	0.05	28.25	0.12	-25.54
1500	0.23	-174.85	7.78	75.66	0.05	26.86	0.15	-29.69

#### (Vd=3.0V,Id = 27mA, T = 25 $^{\circ}$ C, calibrated to device leads)

Freq	S11	S11	S21	S21	S12	S12	S22	S22
[MHz]	Mag	Ang	Mag	Ang	Mag	Ang	Mag	Ang
500	0.26	-75.46	15.48	141.37	0.04	55.53	0.26	-88.42
600	0.31	-107.06	13.30	127.53	0.05	45.23	0.17	-102.44
700	0.34	-122.34	11.75	118.21	0.04	38.40	0.11	-104.33
800	0.35	-131.66	10.55	110.48	0.04	35.85	0.08	-95.78
900	0.35	-138.83	9.63	104.26	0.04	31.10	0.07	-76.19
1000	0.35	-143.86	8.88	98.67	0.05	28.25	0.08	-58.96
1100	0.35	-148.58	8.25	93.39	0.05	25.15	0.11	-50.97
1200	0.35	-151.32	7.70	88.38	0.05	24.09	0.13	-47.09
1300	0.35	-153.89	7.23	83.57	0.05	22.66	0.16	-47.34
1400	0.34	-156.28	6.81	78.98	0.05	22.68	0.19	-48.71
1500	0.34	-158.25	6.44	74.59	0.05	19.77	0.21	-49.29

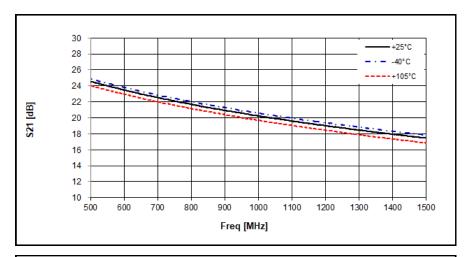
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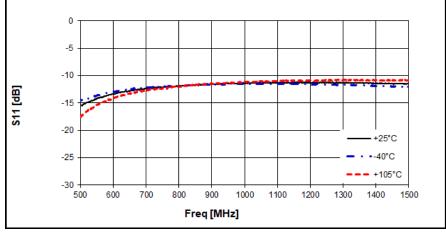


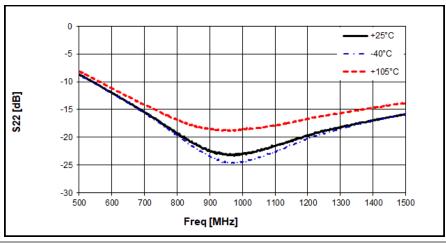


# **Typical Performance**

 $V_d = 5V, I_d = 66mA$ 



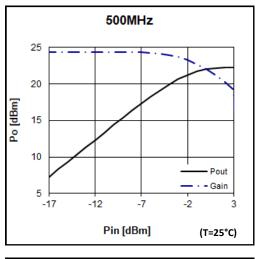


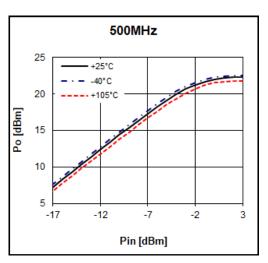


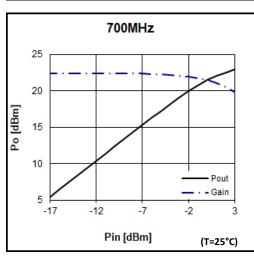


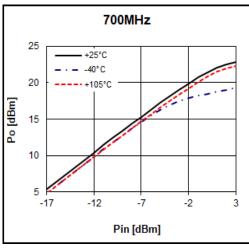


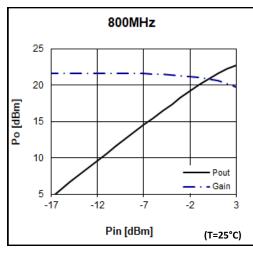


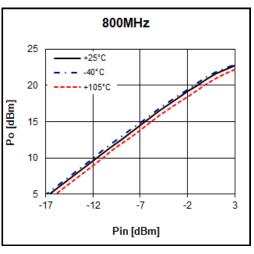








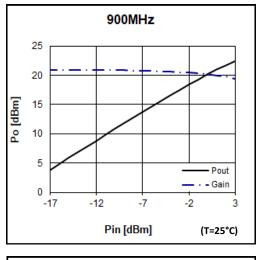


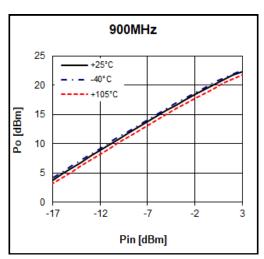


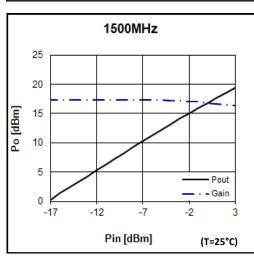


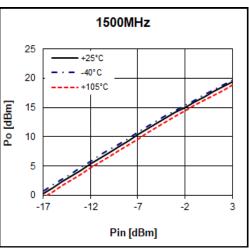


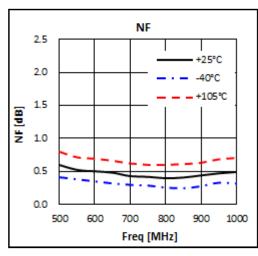
#### $V_d = 5V$ , $I_d = 66mA$

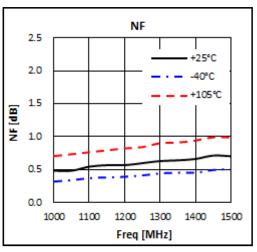








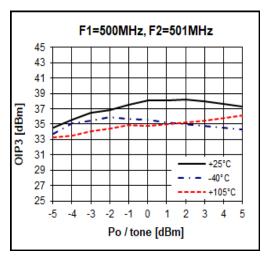


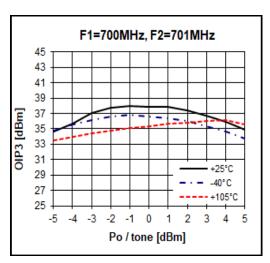


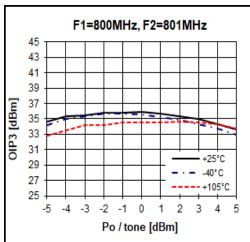


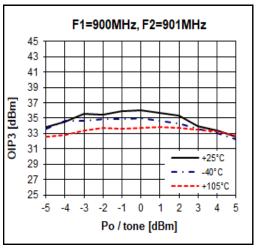


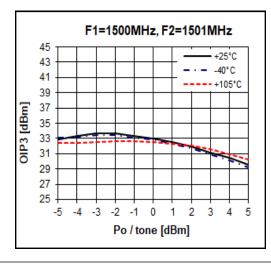
#### $V_d = 5V$ , $I_d = 66mA$

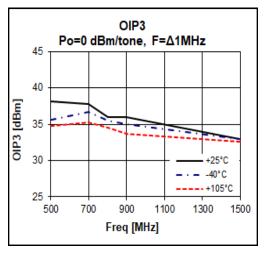










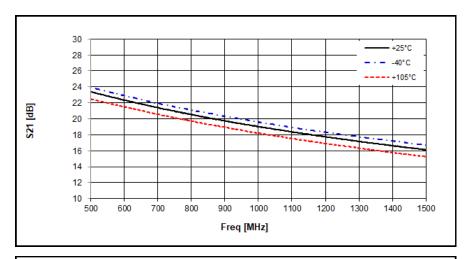


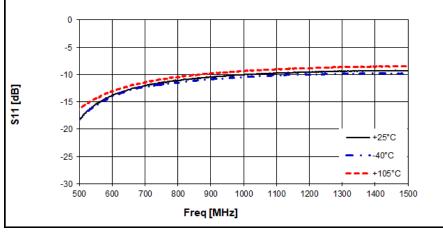


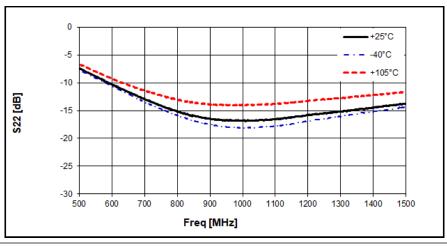


# **Typical Performance**

 $V_d = 3V$ ,  $I_d = 27mA$ 



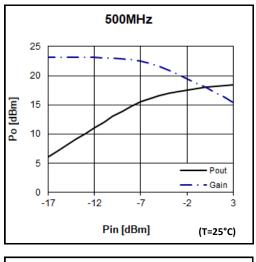


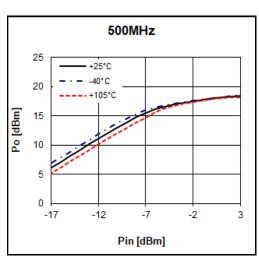


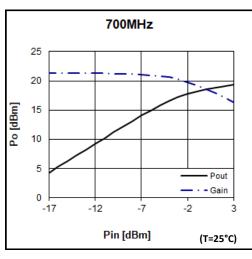


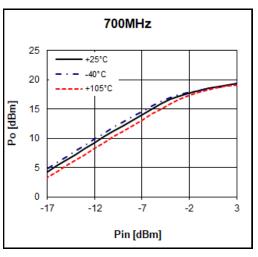


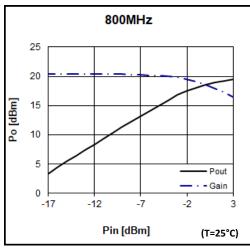
 $V_d = 3V$ ,  $I_d = 27mA$ 

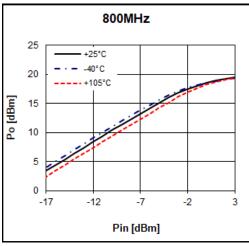








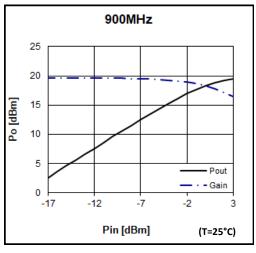


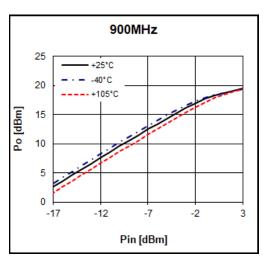


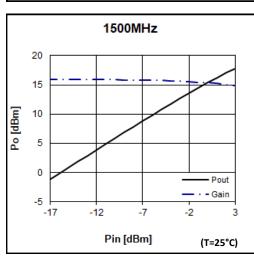


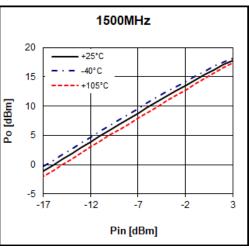


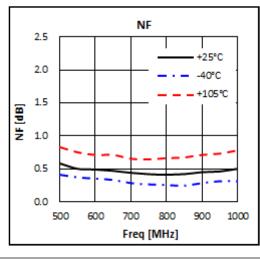
 $V_d = 3V$ ,  $I_d = 27mA$ 

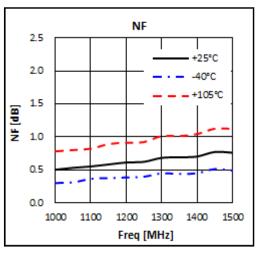








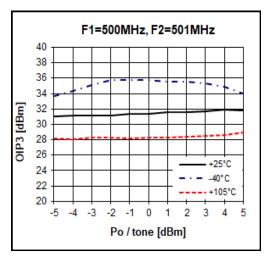


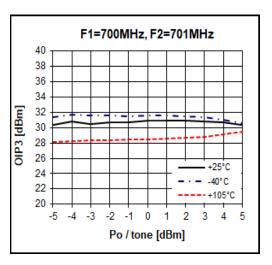


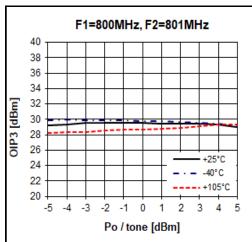


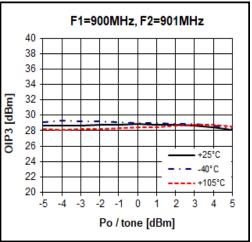


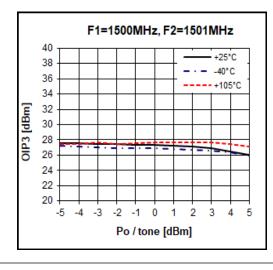
 $V_d = 3V, I_d = 27mA$ 

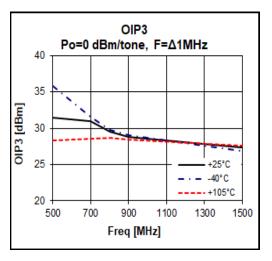














# **Enable Application**

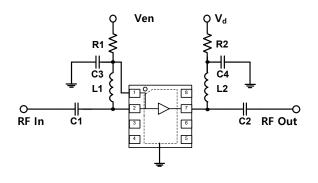
## **State function**

Vd	Ven	State
5V	0V	Off
5V	5V	On

## **Switching Time**

	Min.	Typical	Max.	Unit
Raising time (T <sub>on</sub> )		140		ns
Falling time (T <sub>off</sub> )		140		ns

## **Application circuit**



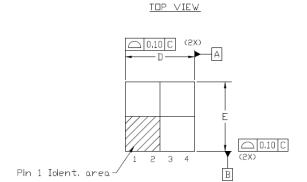
#### **BOM**

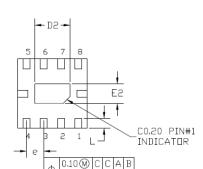
Component	Value	Size	Vendor
C1,C4	100pF	0603	Samsung
C2,C3	12pF	0603	Samsung
R1	6.8Kohm	0603	Samsung
R2	0 ohm	0603	Samsung
L1	27nH	0603	Taiyo Yuden
L2	82nH	0603	Taiyo Yuden

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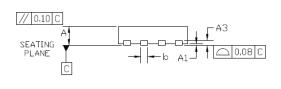


## **Package Outline Dimension**





BOTTOM VIEW



SIDE VIEW

СПММПИ DIMENSIONS MILLIMETER DIMENSIONS INCH MAX. MIN. N□M. MIN. N□M. Α 0.50 0.60 0.020 0.022 0.024 0.55 0.150 REF 0.006 REF Α1 0.02 0.05 0.000 0.001 b 0.20 0.25 0.006 0.008 D 2.10 0.075 0.083 0.044 D2 0.92 1.02 1.12 1.90 2.00 2.10 0.075 0.079 0.083 Ε E2 0,56 0.66 0.018 0.022 0.026 0.50 BS0 0.020 BSC 0.29 0.30 0.011

#### NOTES

- 1. DIMENSION AND TOLERANCING CONFORM TO ASME Y14.5M-1994.
- CONTROLLING DIMENSIONS : MILLIMETER, CONVERTED INCH DIMENSION ARE NOT NECESSARILY EXACT.

# **Suggested PCB Land Pattern and PAD Layout**

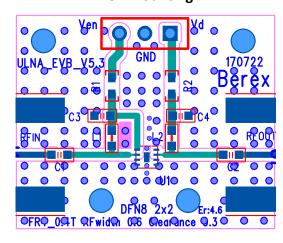
#### **PCB Land Pattern**

# 0.2500 R0.1500 R0.1500 R0.1500 R0.2500 R0.2500

PCB lay out \_ on BeRex website

Note: All dimension \_ millimeters

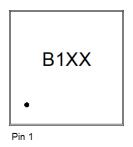
## **PCB Mounting**







# **Package Marking**

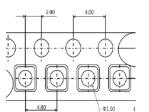


XX = Wafer No.

## Tape & Reel

**DFN8 2x2** 

Packaging information:



Tape Width (mm): 8

Reel Size (inches): 7

Device Cavity Pitch (mm): 4

Devices Per Reel: 3000

## Lead plating finish

100% Tin Matte finish

(All BeRex products undergoes a 1 hour, 150 degree C, Anneal bake to eliminate thin whisker growth concerns.)

## MSL / ESD Rating

**ESD Rating:** Class 1C

Value: Passes <2000V

Test: Human Body Model (HBM)

Standard: JEDEC Standard JS-001-2014

MSL Rating: Level 1 at +260°C convection reflow

Standard: JEDEC Standard J-STD-020



Proper ESD procedures should be followed when handling this device.

Rev. 6.6





## **RoHS Compliance**

This part is compliant with Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) Directive 2011/65/EU as amended by Directive 2015/863/EU. This product also is compliant with a concentration of the Substances of Very High Concern (SVHC) candidate list which are contained in a quantity of less than 0.1%(w/w) in each components of a product and/or its packaging placed on the European Community market by the BeRex and Suppliers.

## **NATO CAGE code:**

|--|